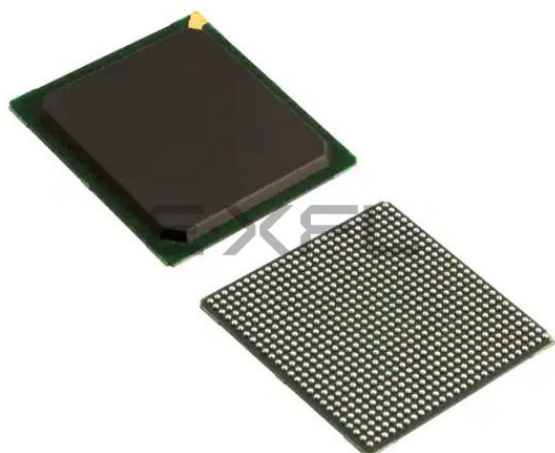




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	404
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-5fgg676c



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview

DS083 (v5.0) June 21, 2011

Product Specification

Summary of Virtex-II Pro™ / Virtex-II Pro X Features

- High-Performance Platform FPGA Solution, Including
 - Up to twenty RocketIO™ or RocketIO X embedded Multi-Gigabit Transceivers (MGTS)
 - Up to two IBM PowerPC™ RISC processor blocks
 - Based on Virtex-II™ Platform FPGA Technology
 - Flexible logic resources
 - SRAM-based in-system configuration
 - Active Interconnect technology
 - SelectRAM™+ memory hierarchy
 - Dedicated 18-bit x 18-bit multiplier blocks
 - High-performance clock management circuitry
 - SelectIO™-Ultra technology
 - XCITE Digitally Controlled Impedance (DCI) I/O
- Virtex-II Pro / Virtex-II Pro X family members and resources are shown in [Table 1](#).

Table 1: Virtex-II Pro / Virtex-II Pro X FPGA Family Members

Device ⁽¹⁾	RocketIO Transceiver Blocks	PowerPC Processor Blocks	Logic Cells ⁽²⁾	CLB (1 = 4 slices = max 128 bits)		18 X 18 Bit Multiplier Blocks	Block SelectRAM+		DCMs	Maximum User I/O Pads
				Slices	Max Distr RAM (Kb)		18 Kb Blocks	Max Block RAM (Kb)		
XC2VP2	4	0	3,168	1,408	44	12	12	216	4	204
XC2VP4	4	1	6,768	3,008	94	28	28	504	4	348
XC2VP7	8	1	11,088	4,928	154	44	44	792	4	396
XC2VP20	8	2	20,880	9,280	290	88	88	1,584	8	564
XC2VPX20	8 ⁽⁴⁾	1	22,032	9,792	306	88	88	1,584	8	552
XC2VP30	8	2	30,816	13,696	428	136	136	2,448	8	644
XC2VP40	0 ⁽³⁾ , 8, or 12	2	43,632	19,392	606	192	192	3,456	8	804
XC2VP50	0 ⁽³⁾ or 16	2	53,136	23,616	738	232	232	4,176	8	852
XC2VP70	16 or 20	2	74,448	33,088	1,034	328	328	5,904	8	996
XC2VPX70	20 ⁽⁴⁾	2	74,448	33,088	1,034	308	308	5,544	8	992
XC2VP100	0 ⁽³⁾ or 20	2	99,216	44,096	1,378	444	444	7,992	12	1,164

Notes:

- 7 speed grade devices are not available in Industrial grade.
- Logic Cell $\approx$ (1) 4-input LUT + (1)FF + Carry Logic
- These devices can be ordered in a configuration without RocketIO transceivers. See [Table 3](#) for package configurations.
- Virtex-II Pro X devices equipped with RocketIO X transceiver cores.

RocketIO X Transceiver Features (XC2VPX20 and XC2VPX70 Only)

- Variable-Speed Full-Duplex Transceiver (XC2VPX20) Allowing 2.488 Gb/s to 6.25 Gb/s Baud Transfer Rates.
 - Includes specific baud rates used by various standards, as listed in [Table 4, Module 2](#).
- Fixed-Speed Full-Duplex Transceiver (XC2VPX70) Operating at 4.25 Gb/s Baud Transfer Rate.
- Eight or Twenty Transceiver Modules on an FPGA, Depending upon Device
- Monolithic Clock Synthesis and Clock Recovery
 - Eliminates the need for external components
- Automatic Lock-to-Reference Function
- Programmable Serial Output Differential Swing
 - 200 mV to 1600 mV, peak-peak
 - Allows compatibility with other serial system voltage levels
- Programmable Pre-emphasis Levels 0 to 500%
- Telecom/Datacom Support Modes
 - "x8" and "x10" clocking/data paths
 - 64B/66B clocking support

The Trace port provides instruction execution trace information to an external trace tool. The PPC405 core is capable of back trace and forward trace. Back trace is the tracing of instructions prior to a debug event while forward trace is the tracing of instructions after a debug event.

The processor JTAG port and the FPGA JTAG port can be accessed independently, or the two can be programmatically linked together and accessed via the dedicated FPGA JTAG pins.

For detailed information on the PPC405 JTAG interface, please refer to the "JTAG Interface" section of the [PowerPC 405 Processor Block Reference Guide](#)

CoreConnect™ Bus Architecture

The Processor Block is compatible with the CoreConnect™ bus architecture. Any CoreConnect compliant cores including Xilinx soft IP can integrate with the Processor Block through this high-performance bus architecture implemented on FPGA fabric.

The CoreConnect architecture provides three buses for interconnecting Processor Blocks, Xilinx soft IP, third party IP, and custom logic, as shown in [Figure 15](#):

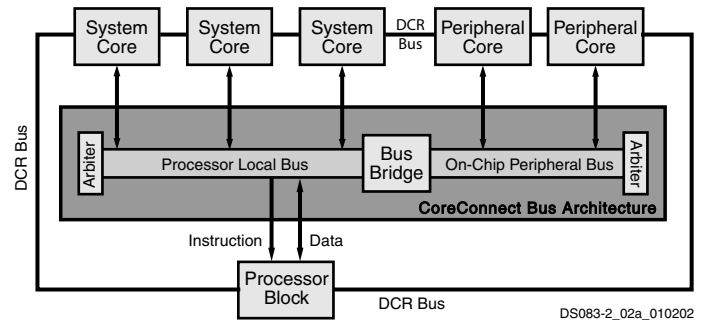


Figure 15: CoreConnect Block Diagram

- Processor Local Bus (PLB)
- On-Chip Peripheral Bus (OPB)
- Device Control Register (DCR) bus

High-performance peripherals connect to the high-bandwidth, low-latency PLB. Slower peripheral cores connect to the OPB, which reduces traffic on the PLB, resulting in greater overall system performance.

For more information, refer to:

http://www-3.ibm.com/chips/techlib/techlib.nfs/productfamilies/CoreConnect_Bus_Architecture/

Functional Description: Embedded PowerPC 405 Core

This section offers a brief overview of the various functional blocks shown in [Figure 16](#).

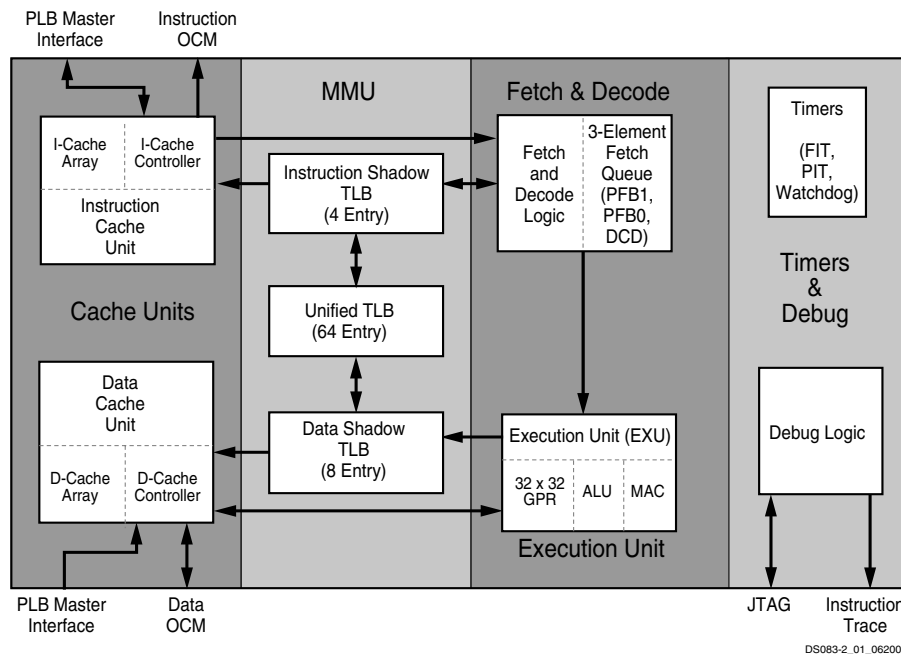


Figure 16: Embedded PPC405 Core Block Diagram

Embedded PPC405 Core

The embedded PPC405 core is a 32-bit Harvard architecture processor. [Figure 16](#) illustrates its functional blocks:

- Cache units
- Memory Management unit
- Fetch Decode unit

Configurable Logic Blocks (CLBs)

The Virtex-II Pro configurable logic blocks (CLB) are organized in an array and are used to build combinatorial and synchronous logic designs. Each CLB element is tied to a switch matrix to access the general routing matrix, as shown in [Figure 32](#). A CLB element comprises 4 similar slices, with fast local feedback within the CLB. The four slices are split in two columns of two slices with two independent carry logic chains and one common shift chain.

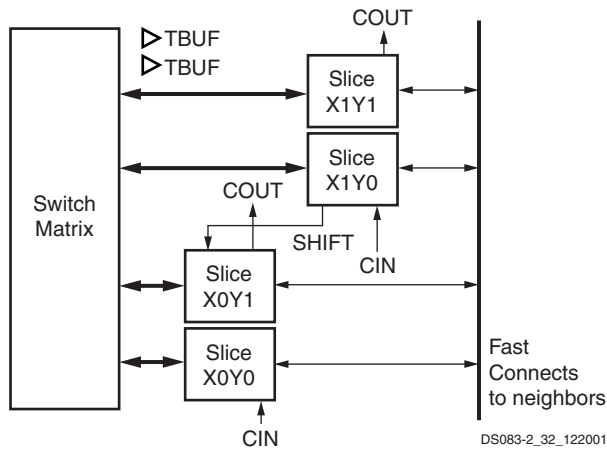


Figure 32: Virtex-II Pro CLB Element

Slice Description

Each slice includes two 4-input function generators, carry logic, arithmetic logic gates, wide function multiplexers and two storage elements. As shown in [Figure 33](#), each 4-input function generator is programmable as a 4-input LUT, 16 bits of distributed SelectRAM+ memory, or a 16-bit variable-tap shift register element.

The output from the function generator in each slice drives both the slice output and the D input of the storage element. [Figure 34](#) shows a more detailed view of a single slice.

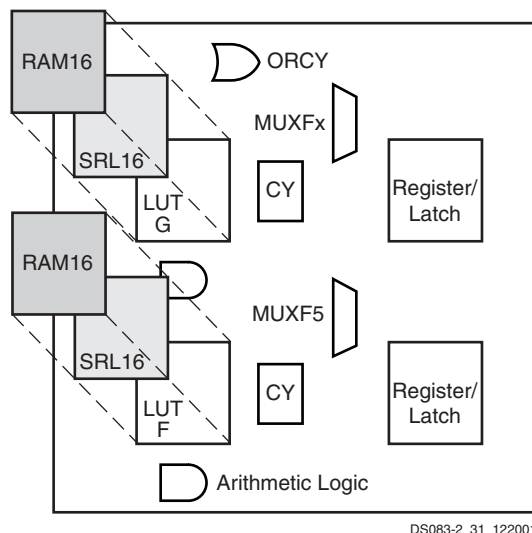


Figure 33: Virtex-II Pro Slice Configuration

Configurations

Look-Up Table

Virtex-II Pro function generators are implemented as 4-input look-up tables (LUTs). Four independent inputs are provided to each of the two function generators in a slice (F and G). These function generators are each capable of implementing any arbitrarily defined boolean function of four inputs. The propagation delay is therefore independent of the function implemented. Signals from the function generators can exit the slice (X or Y output), can input the XOR dedicated gate (see arithmetic logic), or input the carry-logic multiplexer (see fast look-ahead carry logic), or feed the D input of the storage element, or go to the MUXF5 (not shown in [Figure 34](#)).

In addition to the basic LUTs, the Virtex-II Pro slice contains logic (MUXF5 and MUXFx multiplexers) that combines function generators to provide any function of five, six, seven, or eight inputs. The MUXFx is either MUXF6, MUXF7, or MUXF8 according to the slice considered in the CLB. Selected functions up to nine inputs (MUXF5 multiplexer) can be implemented in one slice. The MUXFx can also be a MUXF6, MUXF7, or MUXF8 multiplexer to map any function of six, seven, or eight inputs and selected wide logic functions.

Register/Latch

The storage elements in a Virtex-II Pro slice can be configured either as edge-triggered D-type flip-flops or as level-sensitive latches. The D input can be directly driven by the X or Y output via the DX or DY input, or by the slice inputs bypassing the function generators via the BX or BY input. The clock enable signal (CE) is active High by default. If left unconnected, the clock enable for that storage element defaults to the active state.

In addition to clock (CK) and clock enable (CE) signals, each slice has set and reset signals (SR and BY slice inputs). SR forces the storage element into the state specified by the attribute SRHIGH or SRLOW. SRHIGH forces a logic 1 when SR is asserted. SRLOW forces a logic 0. When SR is used, an optional second input (BY) forces the storage element into the opposite state via the REV pin. The reset condition is predominant over the set condition. (See [Figure 35](#).)

The initial state after configuration or global initial state is defined by a separate INIT0 and INIT1 attribute. By default, setting the SRLOW attribute sets INIT0, and setting the SRHIGH attribute sets INIT1. For each slice, set and reset can be set to be synchronous or asynchronous. Virtex-II Pro devices also have the ability to set INIT0 and INIT1 independent of SRHIGH and SRLOW.

The control signals clock (CLK), clock enable (CE) and set/reset (SR) are common to both storage elements in one slice. All of the control signals have independent polarity. Any inverter placed on a control input is automatically absorbed.

Master SelectMAP Mode

This mode is a master version of the SelectMAP mode. The device is configured byte-wide on a CCLK supplied by the Virtex-II Pro FPGA device. Timing is similar to the Slave SerialMAP mode except that CCLK is supplied by the Virtex-II Pro FPGA.

Boundary-Scan (JTAG, IEEE 1532) Mode

In Boundary-Scan mode, dedicated pins are used for configuring the Virtex-II Pro device. The configuration is done entirely through the IEEE 1149.1 Test Access Port (TAP).

Virtex-II Pro device configuration using Boundary-Scan is compatible with with IEEE 1149.1-1993 standard and the new IEEE 1532 standard for In-System Configurable (ISC) devices. The IEEE 1532 standard is backward compliant with the IEEE 1149.1-1993 TAP and state machine. The IEEE Standard 1532 for In-System Configurable (ISC) devices is intended to be programmed, reprogrammed, or tested on the board via a physical and logical protocol. Configuration through the Boundary-Scan port is always available, independent of the mode selection. Selecting the Boundary-Scan mode simply turns off the other modes.

Table 32: Virtex-II Pro Configuration Mode Pin Settings

Configuration Mode ⁽¹⁾	M2	M1	M0	CCLK Direction	Data Width	Serial D _{OUT} ⁽²⁾
Master Serial	0	0	0	Out	1	Yes
Slave Serial	1	1	1	In	1	Yes
Master SelectMAP	0	1	1	Out	8	No
Slave SelectMAP	1	1	0	In	8	No
Boundary-Scan	1	0	1	N/A	1	No

Notes:

1. The HSWAP_EN pin controls the pull-ups. Setting M2, M1, and M0 selects the configuration mode, while the HSWAP_EN pin controls whether or not the pull-ups are used.
2. Daisy chaining is possible only in modes where Serial D_{OUT} is used. For example, in SelectMAP modes, the first device does NOT support daisy chaining of downstream devices.

Table 33 lists the default total number of bits required to configure each device.

Table 33: Virtex-II Pro Default Bitstream Lengths

Device	Number of Configuration Bits
XC2VP2	1,305,376
XC2VP4	3,006,496
XC2VP7	4,485,408
XC2VP20	8,214,560
XC2VPX20	8,214,560
XC2VP30	11,589,920
XC2VP40	15,868,192
XC2VP50	19,021,344
XC2VP70	26,098,976
XC2VPX70	26,098,976
XC2VP100	34,292,768

Configuration Sequence

The configuration of Virtex-II Pro devices is a three-phase process. First, the configuration memory is cleared. Next, configuration data is loaded into the memory, and finally, the logic is activated by a start-up process.

Configuration is automatically initiated on power-up unless it is delayed by the user. The INIT_B pin can be held Low using an open-drain driver. An open-drain is required since INIT_B is a bidirectional open-drain pin that is held Low by a Virtex-II Pro FPGA device while the configuration memory is being cleared. Extending the time that the pin is Low causes the configuration sequencer to wait. Thus, configuration is delayed by preventing entry into the phase where data is loaded.

The configuration process can also be initiated by asserting the PROG_B pin. The end of the memory-clearing phase is signaled by the INIT_B pin going High, and the completion of the entire process is signaled by the DONE pin going High. The Global Set/Reset (GSR) signal is pulsed after the last frame of configuration data is written but before the start-up sequence. The GSR signal resets all flip-flops on the device.

The default start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary. One CCLK cycle later, the Global Write Enable (GWE) signal is released. This permits the internal storage elements to begin changing state in response to the logic and the user clock.

The relative timing of these events can be changed via configuration options in software. In addition, the GTS and GWE events can be made dependent on the DONE pins of multiple devices all going High, forcing the devices to start

Date	Version	Revision
03/24/03	2.5.1	Table 10: Corrected I/O standard names SSTL18_I and SSTL18_II to SSTL18_I_DCI and SSTL18_II_DCI respectively. Figure 61, text below: Corrected wording of criteria for clock switching.
05/27/03	2.6	- Removed Compatible Output Standards and Compatible Input Standards tables. - Added new Table 12, Summary of Voltage Supply Requirements for All Input and Output Standards. This table replaces deleted I/O standards tables. - Corrected sentence in section Input/Output Individual Options, page 27, to read "The optional weak-keeper circuit is connected to each <i>user I/O pad</i>." - Added section Rules for Combining I/O Standards in the Same Bank, page 29.
06/02/03	2.7	- Added four Differential Termination I/O standards to Table 9 and Table 12. - Added section On-Chip Differential Termination and Figure 31, page 34.
08/25/03	2.7.1	Added footnote referring to XAPP659 to 3.3V I/O callouts in Table 8 and Table 12.
09/10/03	2.8	Section Configuration, page 56: Added text indicating that the mode pins M0-M2 must be held to a constant DC level during and after configuration.
10/14/03	2.9	- Deleted section Functional Description: RocketIO Multi-Gigabit Transceiver (MGT), page 10. Added section Local Clocking, page 51. - Sections Slave-Serial Mode and Master-Serial Mode, page 56: Changed "rising" to "falling" edge with respect to DOUT. Table 8, page 24 and Table 10, page 25: Corrected Input V_{REF} for HSTL_III-IV_18 from 1.08V to 1.1V.
12/10/03	3.0	XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to Production status.
02/19/04	3.1	Section BUFGMUX, page 50: Corrected the definition of the "presently selected clock" to be I0 or I1. Corrected signal names in Figure 61 and associated text from CLK0 and CLK1 to I0 and I1.
03/09/04	3.1.1	Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
04/22/04	3.2	Section Clock De-skew, page 52: Removed reference to CLK2X as an option for DCM clock feedback.
06/30/04	4.0	Merged in DS110-2 (Module 2 of Virtex-II Pro X data sheet). Separate RocketIO and RocketIO X sections created.
11/17/04	4.1	Figure 11, page 12: Corrected figure by removing coupling capacitors from input. - Section Rules for Combining I/O Standards in the Same Bank, page 29: Corrected I/O standard in the first example from LVDS_25_DCI to LVDS_25.
03/01/05	4.2	- Reassigned heading hierarchies for better agreement with content. Table 7: Corrected VCCAUTX and VCCAUXRX to AVCCAUTX and AVCCAUXRX respectively. Table 9: Corrected V_{OD} (output voltage) range for LVDSEXT_25. Table 25: Corrected SelectRAM+ memory available for XC2VPX70 device. Table 33: Updated configuration default bitstream lengths.
06/20/05	4.3	<i>No changes in Module 2 for this revision.</i>
09/15/05	4.4	Table 1: Deleted SONET OC-192 protocol. Table 3: Deleted RocketIO X primitives for SONET OC-192, 10 Gbit Ethernet, and Xilinx 10G (Aurora) protocols. - Changed all instances of 10.3125 Gb/s to 6.25 Gb/s. Table 7: Changed RocketIO X VCCAUXRX from 1.5V globally to 1.5V for 8B/10B encoding, 1.8V for all other encoding protocols.

Table 25: RocketIO Receiver Switching Characteristics

Description	Symbol	Conditions	Min	Typ	Max	Units
Receive total jitter tolerance	T_{JTOL}	2.126 Gb/s – 3.125 Gb/s			0.65	UI ⁽¹⁾
		1.0626 Gb/s – 2.125 Gb/s			0.65	UI
		1.0 Gb/s – 1.0625 Gb/s			0.68	UI
		600 Mb/s – 999 Mb/s			0.68 ⁽²⁾	UI
Receive deterministic jitter tolerance	T_{DJTOL}	2.126 Gb/s – 3.125 Gb/s			0.41	UI
		1.0626 Gb/s – 2.125 Gb/s			0.43	UI
		1.0 Gb/s – 1.0625 Gb/s			0.47	UI
		600 Mb/s – 999 Mb/s			0.47 ⁽²⁾	
Receive latency ⁽³⁾	T_{RXLAT}			25	42 ⁽⁴⁾	RXUSRCLK cycles
RXUSRCLK duty cycle	T_{RXDC}		45	50	55	%
RXUSRCLK2 duty cycle	T_{RX2DC}		45	50	55	%

Notes:

1. UI = Unit Interval
2. The oversampling techniques described in [XAPP572](#) are required to meet these specifications for serial rates less than 1 Gb/s.
3. Receive latency delay RXP/RXN to RXDATA. Refer to [RocketIO Transceiver User Guide](#) for more information on calculating latency.
4. This maximum may occur when certain conditions are present and clock correction and channel bonding are enabled. If these functions are both disabled, the maximum will be near the typical values.

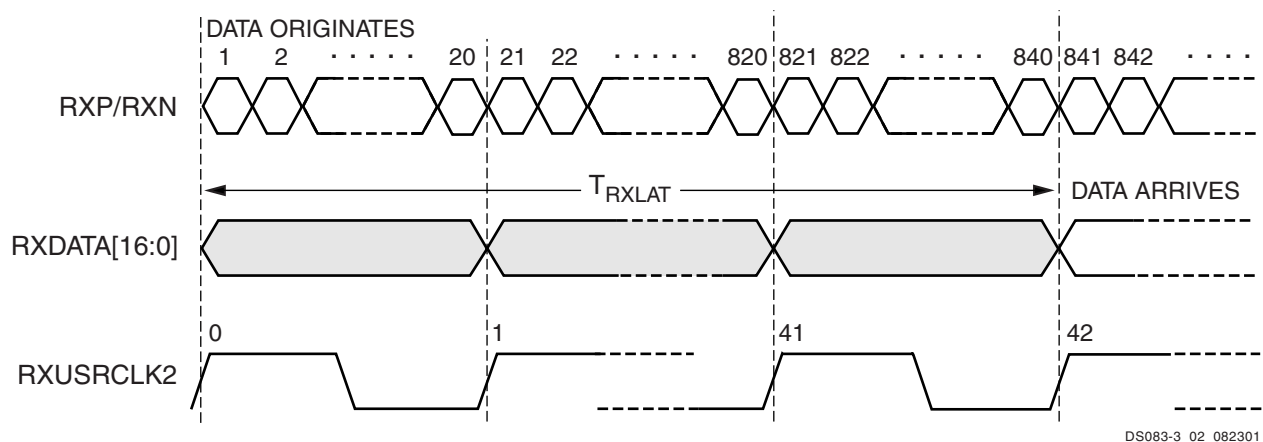


Figure 4: RocketIO Receive Latency (Maximum)

Table 26: RocketIO X Transmitter Switching Characteristics⁽¹⁾

Description	Symbol	Conditions	BREFCLK Frequency	Min	Typ	Max	Units
Serial data rate	F _{GTX}			2.488		6.25	Gb/s
Serial data output total jitter (p-p) ⁽³⁾	T _{TJ}	2.488 Gb/s			0.15	0.20	UI ⁽²⁾
		3.125 Gb/s			0.14	0.19	UI
		4.25 Gb/s			0.39	0.48	UI
		6.25 Gb/s			0.42	0.54	UI
Serial data output deterministic jitter (p-p) ⁽³⁾	T _{DJ}	2.488 Gb/s	155.52 MHz		0.03	0.17	UI
		3.125 Gb/s	156.25 MHz		0.03	0.17	UI
		4.25 Gb/s	212.5 MHz		0.14	0.26	UI
		6.25 Gb/s	312.5 MHz		0.17	0.35	UI
Serial data output random jitter (p-p) ^(3,4)	T _{RJ}	2.488 Gb/s	155.52 MHz		0.12	0.18	UI
		3.125 Gb/s	156.25 MHz		0.12	0.20	UI
		4.25 Gb/s	212.5 MHz		0.25	0.39	UI
		6.25 Gb/s	312.5 MHz		0.25	0.39	UI
TX rise time	T _{RTX}	20% – 80% @ 2.500 Gb/s			60		ps
TX fall time	T _{FTX}				60		ps
Transmit latency ⁽⁵⁾	T _{TXLAT}				14	19	TXUSR CLK cycles
TXUSRCLK duty cycle	T _{TXDC}			45	50	55	%
TXUSRCLK2 duty cycle	T _{TX2DC}			45	50	55	%

Notes:

1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Total Jitter T_{TJ} = T_{DJ} + T_{RJ}
4. T_{RJ} specifications are *wideband* and include low-frequency jitter components (also referred to as *wander*). T_{RJ} specified is peak-to-peak, estimated at BER=10⁻¹² using the Bathtub Method.
5. Transmit latency delay TXDATA to TXP/TXN. Refer to [RocketIO X Transceiver User Guide](#) for more information on calculating latency.

JTAG Test Access Port Switching Characteristics

Characterization data for some of the most commonly requested timing parameters shown in Figure 11 is listed in Table 52.

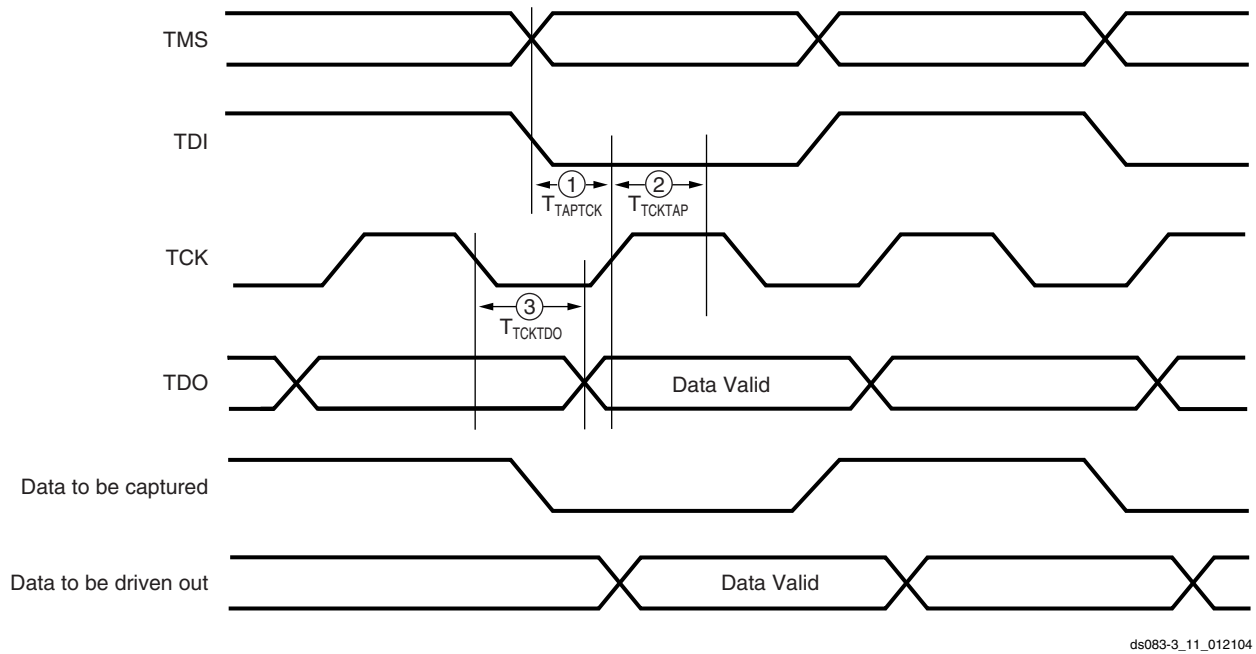


Figure 11: Virtex-II Pro Boundary Scan Port Timing Waveforms

Table 52: Boundary-Scan Port Timing Specifications

	Description	Figure References	Symbol	Value	Units
TCK	TMS and TDI setup time	1	T_{TAPTCK}	5.5	ns, min
	TMS and TDI hold times	2	T_{TCKTAP}	2.0	ns, min
	Falling edge to TDO output valid	3	T_{TCKTDO}	11.0	ns, max
	Maximum frequency		F_{TCK}	33.0	MHz, max

Table 65: Package Skew

Description	Symbol	Device/Package	Value	Units
Package Skew ⁽¹⁾	$T_{PKGSKEW}$	XC2VP2FF672	104	ps
		XC2VP4FF672	102	ps
		XC2VP7FF672	92	ps
		XC2VP7FF896	101	ps
		XC2VP20FF896	93	ps
		XC2VPX20FF896	93	ps
		XC2VP20FF1152	106	ps
		XC2VP30FF896	86	ps
		XC2VP30FF1152	112	ps
		XC2VP40FF1152	92	ps
		XC2VP40FF1148	100	ps
		XC2VP50FF1152	88	ps
		XC2VP50FF1148	101	ps
		XC2VP50FF1517	97	ps
		XC2VP70FF1517	95	ps
		XC2VP70FF1704	101	ps
		XC2VPX70FF1704	101	ps
		XC2VP100FF1704	86	ps
		XC2VP100FF1696	100	ps

Notes:

- These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball (7.1ps per mm).
- Package trace length information is available for these device/package combinations. This information can be used to deskew the package.

Table 66: Sample Window

Description	Symbol	Device	Speed Grade			Units
			-7	-6	-5	
Sampling Error at Receiver Pins ⁽¹⁾	T_{SAMP}	All	0.50	0.50	0.50	ns

Notes:

- This parameter indicates the total sampling error of Virtex-II Pro DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation.
- These measurements include:
 - CLK0 and CLK180 DCM jitter
 - Worst-case duty-cycle distortion, T_{DCD_CLK180}
 - DCM accuracy (phase offset)
 - DCM phase shift resolution
These measurements do not include package or clock tree skew.

Date	Version	Revision
08/25/03	2.9	- Updated time and frequency parameters as per speedsfile v1.81. Table 1: Footnote (2) rewritten to specify “one or more banks.” Table 2: Added footnote referring to XAPP659 for 3.3V I/O operation. Table 53 and Table 54: Revised test setup footnote to refer to Figure 6. Previously specified a capacitive load parameter. Table 57: Due to a document compilation error in v2.8, some DCM parameters were erroneously omitted from the full data sheet file (all four modules concatenated), though not from the stand-alone Module 3 file. The omitted parameters have been restored. Table 64 and Table 66: Corrected parameters to expression in picoseconds, as labeled. Previously expressed in nanoseconds, but labeled picoseconds. Figure 6: Added note to figure regarding termination resistors. Table 5: Added $I_{CCINTMIN}$ for XC2VP30 device.
09/10/03	2.10	Figure 7: Changed representation of mode pins M0, M1, and M2 indicating that they must be held to a constant DC level during and after configuration. Table 49: Added footnote indicating that mode pins M0, M1, and M2 must be held to a constant DC level during and after configuration.
10/14/03	2.11	Table 1: Deleted Footnote (2), which had derated the absolute maximum T_J when one or more banks operated at 3.3V. Changed T_J description from “Operating junction temperature” to “Maximum junction temperature”. Added new Footnote (2) linking to website for package thermal data. Table 4 and Table 5: Filled in power-on and quiescent current parameters for all devices through XC2VP70. Added Industrial Grade multiplier specification to Footnote (1) in both tables. - In section General Power Supply Requirements, replaced reference to Answer Record 11713 with reference to XAPP689 regarding handling of simultaneously switching outputs (SSO). - In section I/O Standard Adjustment Measurement Methodology: Table 39 renamed Input Delay Measurement Methodology. Added footnotes. - Added new Table 40, Output Delay Measurement Methodology. - Replaced Figure 6, Generalized Test Setup, with new drawing. - Revised and extended text describing output delay measurement procedure. Table 58: For Input Clock Low/High Pulse Width, PSCLK and CLKIN, changed existing Footnote (2) to new Footnote (3).
11/10/03	2.12	Table 1: Changed 3.3V absolute max V_{IN} and V_{TS} from 3.75V to 4.05V. Added footnote referring to XAPP659. Table 4: Removed MIN column from table.
12/05/03	3.0	- XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, updated and released to Production status as per speedsfile v1.83. Featured changes: - Speedsfile parameter values for -7 speed grade added for devices XC2VP2-XC2VP70. Table 13 and Table 14: Pin-to-pin and register-to_register performance parameter values added. Table 64: New parameter T_{DCD_LOCAL} (and footnote) replaces T_{DCD_CLK0}. - All remaining source-synchronous parameter values added (Table 64 & following).

Table 5: FG256/FGG256 — XC2VP2 and XC2VP4

Bank	Pin Description	Pin Number
N/A	GND	R15
N/A	GND	L6
N/A	GND	L11
N/A	GND	K9
N/A	GND	K8
N/A	GND	K7
N/A	GND	K10
N/A	GND	J9
N/A	GND	J8
N/A	GND	J7
N/A	GND	J10
N/A	GND	H9
N/A	GND	H8
N/A	GND	H7
N/A	GND	H10
N/A	GND	G9
N/A	GND	G8
N/A	GND	G7
N/A	GND	G10
N/A	GND	F6
N/A	GND	F11
N/A	GND	B2
N/A	GND	B15
N/A	GND	A16
N/A	GND	A1

Notes:

1. See Table 4 for an explanation of the signals available on this pin.

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
1	IO_L45N_1/VREF_1	C18			
1	IO_L45P_1	D18			
1	IO_L43N_1	E18			
1	IO_L43P_1	F18			
1	IO_L39N_1	G18			
1	IO_L39P_1	H18			
1	IO_L37N_1	A19			
1	IO_L37P_1	B19			
1	IO_L09N_1/VREF_1	E19			
1	IO_L09P_1	F19			
1	IO_L07N_1	G19			
1	IO_L07P_1	H19			
1	IO_L06N_1	C20			
1	IO_L06P_1	D20			
1	IO_L05_1/No_Pair	E20			
1	IO_L03N_1/VREF_1	F20			
1	IO_L03P_1	G20			
1	IO_L02N_1	D21			
1	IO_L02P_1	E21			
1	IO_L01N_1/VRP_1	D22			
1	IO_L01P_1/VRN_1	E22			
2	IO_L01N_2/VRP_2	C25			
2	IO_L01P_2/VRN_2	C26			
2	IO_L02N_2	D25			
2	IO_L02P_2	D26			
2	IO_L03N_2	E23			
2	IO_L03P_2	F22			
2	IO_L04N_2/VREF_2	E25			
2	IO_L04P_2	E26			
2	IO_L06N_2	F21			
2	IO_L06P_2	G21			
2	IO_L24N_2	F23	NC		
2	IO_L24P_2	F24	NC		
2	IO_L31N_2	F25			

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
2	IO_L48P_2	H1	NC		
2	IO_L49N_2	J7	NC		
2	IO_L49P_2	J6	NC		
2	IO_L50N_2	J5	NC		
2	IO_L50P_2	J4	NC		
2	IO_L51N_2	J3	NC		
2	IO_L51P_2	J2	NC		
2	IO_L52N_2/VREF_2	K6	NC		
2	IO_L52P_2	K5	NC		
2	IO_L53N_2	K4	NC		
2	IO_L53P_2	K3	NC		
2	IO_L54N_2	J1	NC		
2	IO_L54P_2	K1	NC		
2	IO_L55N_2	K7	NC		
2	IO_L55P_2	L8	NC		
2	IO_L56N_2	L7	NC		
2	IO_L56P_2	M7	NC		
2	IO_L57N_2	L6	NC		
2	IO_L57P_2	L5	NC		
2	IO_L58N_2/VREF_2	L4	NC		
2	IO_L58P_2	L3	NC		
2	IO_L59N_2	L2	NC		
2	IO_L59P_2	L1	NC		
2	IO_L60N_2	M8	NC		
2	IO_L60P_2	N8	NC		
2	IO_L85N_2	M6			
2	IO_L85P_2	M5			
2	IO_L86N_2	M4			
2	IO_L86P_2	M3			
2	IO_L87N_2	M2			
2	IO_L87P_2	M1			
2	IO_L88N_2/VREF_2	N7			
2	IO_L88P_2	N6			
2	IO_L89N_2	N5			
2	IO_L89P_2	N4			
2	IO_L90N_2	N3			
2	IO_L90P_2	N2			

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
0	IO_L43N_0	B22		
0	IO_L43P_0	C22		
0	IO_L44N_0	K21		
0	IO_L44P_0	L21		
0	IO_L45N_0	G21		
0	IO_L45P_0/VREF_0	H21		
0	IO_L46N_0	E21		
0	IO_L46P_0	F21		
0	IO_L47N_0	K20		
0	IO_L47P_0	L20		
0	IO_L48N_0	C21		
0	IO_L48P_0	D21		
0	IO_L49N_0	A21		
0	IO_L49P_0	B21		
0	IO_L50_0/No_Pair	G20		
0	IO_L53_0/No_Pair	H19		
0	IO_L54N_0	E20		
0	IO_L54P_0	F20		
0	IO_L55N_0	C20		
0	IO_L55P_0	D19		
0	IO_L56N_0	K19		
0	IO_L56P_0	L19		
0	IO_L57N_0	A20		
0	IO_L57P_0/VREF_0	B20		
0	IO_L66N_0	F19	NC	
0	IO_L66P_0/VREF_0	G19	NC	
0	IO_L67N_0	B19		
0	IO_L67P_0	C19		
0	IO_L68N_0	H18		
0	IO_L68P_0	J18		
0	IO_L69N_0	F18		
0	IO_L69P_0/VREF_0	G18		
0	IO_L73N_0	D18		
0	IO_L73P_0	E18		
0	IO_L74N_0/GCLK7P	K18		
0	IO_L74P_0/GCLK6S	L18		
0	IO_L75N_0/GCLK5P	B18		
0	IO_L75P_0/GCLK4S	C18		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
1	IO_L64N_1	E18		
1	IO_L64P_1	D18		
1	IO_L60N_1	G18		
1	IO_L60P_1	F18		
1	IO_L59N_1	L18		
1	IO_L59P_1	K18		
1	IO_L58N_1	J18		
1	IO_L58P_1	H18		
1	IO_L57N_1/VREF_1	D17		
1	IO_L57P_1	C17		
1	IO_L56N_1	N18		
1	IO_L56P_1	M18		
1	IO_L55N_1	E17		
1	IO_L55P_1	E16		
1	IO_L54N_1	G17		
1	IO_L54P_1	F16		
1	IO_L53_1/No_Pair	J17		
1	IO_L50_1/No_Pair	H17		
1	IO_L49N_1	J16		
1	IO_L49P_1	H16		
1	IO_L48N_1	D15		
1	IO_L48P_1	C15		
1	IO_L47N_1	L17		
1	IO_L47P_1	K16		
1	IO_L46N_1	F15		
1	IO_L46P_1	E15		
1	IO_L45N_1/VREF_1	H15		
1	IO_L45P_1	G15		
1	IO_L44N_1	N17		
1	IO_L44P_1	M17		
1	IO_L43N_1	D14		
1	IO_L43P_1	C14		
1	IO_L39N_1	F14		
1	IO_L39P_1	E14		
1	IO_L38N_1	M16		
1	IO_L38P_1	M15		
1	IO_L37N_1	H14		
1	IO_L37P_1	G14		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
6	IO_L34P_6	AG37		
6	IO_L34N_6	AF37		
6	IO_L35P_6	AE30		
6	IO_L35N_6	AE31		
6	IO_L36P_6	AG33		
6	IO_L36N_6	AG34		
6	IO_L37P_6	AF38		
6	IO_L37N_6	AF39		
6	IO_L38P_6	AD28		
6	IO_L38N_6	AC28		
6	IO_L39P_6	AF35		
6	IO_L39N_6/VREF_6	AF36		
6	IO_L40P_6	AF33		
6	IO_L40N_6	AF34		
6	IO_L41P_6	AD29		
6	IO_L41N_6	AD30		
6	IO_L42P_6	AE38		
6	IO_L42N_6	AE39		
6	IO_L43P_6	AE36		
6	IO_L43N_6	AE37		
6	IO_L44P_6	AC27		
6	IO_L44N_6	AB27		
6	IO_L45P_6	AE34		
6	IO_L45N_6/VREF_6	AE35		
6	IO_L46P_6	AE32		
6	IO_L46N_6	AE33		
6	IO_L47P_6	AC30		
6	IO_L47N_6	AC31		
6	IO_L48P_6	AD37		
6	IO_L48N_6	AD38		
6	IO_L49P_6	AD33		
6	IO_L49N_6	AD34		
6	IO_L50P_6	AB28		
6	IO_L50N_6	AB29		
6	IO_L51P_6	AD36		
6	IO_L51N_6/VREF_6	AC36		
6	IO_L52P_6	AD32		
6	IO_L52N_6	AC32		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
5	IO_L19P_5		AV32		
5	IO_L09N_5/VREF_5		AP32		
5	IO_L09P_5		AR32		
5	IO_L08N_5		AW33		
5	IO_L08P_5		AV33		
5	IO_L07N_5/VREF_5		AT33		
5	IO_L07P_5		AU33		
5	IO_L06N_5/VRP_5		AP33		
5	IO_L06P_5/VRN_5		AR33		
5	IO_L05_5/No_Pair		AN32		
5	IO_L03N_5/D4		AW34		
5	IO_L03P_5/D5		AY34		
5	IO_L02N_5/D6		AV34		
5	IO_L02P_5/D7		AU34		
5	IO_L01N_5/RDWR_B		AR34		
5	IO_L01P_5/CS_B		AT34		
6	IO_L01P_6/VRN_6		AW37		
6	IO_L01N_6/VRP_6		AV37		
6	IO_L02P_6		AW36		
6	IO_L02N_6		AV36		
6	IO_L03P_6		AY37		
6	IO_L03N_6/VREF_6		AY38		
6	IO_L04P_6		AU36		
6	IO_L04N_6		AT37		
6	IO_L05P_6		AU35		
6	IO_L05N_6		AT35		
6	IO_L06P_6		AW41		
6	IO_L06N_6		AW42		
6	IO_L73P_6		AV41		
6	IO_L73N_6		AV42		
6	IO_L74P_6		AW40		
6	IO_L74N_6		AV40		
6	IO_L75P_6		AU39		
6	IO_L75N_6/VREF_6		AU40		
6	IO_L76P_6		AU41		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	RXPPAD21		BB31		
N/A	GNDA21		AY31		
N/A	TXPPAD21		BB32		
N/A	TXNPAD21		BB33		
N/A	VTTXPAD21		BA33		
N/A	AVCCAUXTX21		BA32		
N/A	AVCCAUXRX22		BA34		
N/A	VTRXPAD22		BA35		
N/A	RXNPAD22		BB34		
N/A	RXPPAD22		BB35		
N/A	GNDA22		AY35		
N/A	TXPPAD22		BB36		
N/A	TXNPAD22		BB37		
N/A	VTTXPAD22		BA37		
N/A	AVCCAUXTX22		BA36		
N/A	AVCCAUXRX23		BA38		
N/A	VTRXPAD23		BA39		
N/A	RXNPAD23		BB38		
N/A	RXPPAD23		BB39		
N/A	GNDA23		AY39		
N/A	TXPPAD23		BB40		
N/A	TXNPAD23		BB41		
N/A	VTTXPAD23		BA41		
N/A	AVCCAUXTX23		BA40		
N/A	VCCINT		AB27		
N/A	VCCINT		AB16		
N/A	VCCINT		AC27		
N/A	VCCINT		AC16		
N/A	VCCINT		AD27		
N/A	VCCINT		AD16		
N/A	VCCINT		AE27		
N/A	VCCINT		AE16		
N/A	VCCINT		AF27		
N/A	VCCINT		AF26		
N/A	VCCINT		AF17		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L33N_6/VREF_6	AK40	
6	IO_L34P_6	AK36	
6	IO_L34N_6	AK37	
6	IO_L35P_6	AE36	
6	IO_L35N_6	AE37	
6	IO_L36P_6	AJ41	
6	IO_L36N_6	AJ42	
6	IO_L37P_6	AJ40	
6	IO_L37N_6	AH40	
6	IO_L38P_6	AE34	
6	IO_L38N_6	AE35	
6	IO_L39P_6	AJ38	
6	IO_L39N_6/VREF_6	AH37	
6	IO_L40P_6	AJ36	
6	IO_L40N_6	AJ37	
6	IO_L41P_6	AE32	
6	IO_L41N_6	AE33	
6	IO_L42P_6	AH41	
6	IO_L42N_6	AH42	
6	IO_L43P_6	AH38	
6	IO_L43N_6	AH39	
6	IO_L44P_6	AD36	
6	IO_L44N_6	AC35	
6	IO_L45P_6	AH36	
6	IO_L45N_6/VREF_6	AG36	
6	IO_L46P_6	AG41	
6	IO_L46N_6	AG42	
6	IO_L47P_6	AD34	
6	IO_L47N_6	AC33	
6	IO_L48P_6	AG40	
6	IO_L48N_6	AF39	
6	IO_L49P_6	AG38	
6	IO_L49N_6	AG39	
6	IO_L50P_6	AD32	
6	IO_L50N_6	AD33	
6	IO_L51P_6	AG37	
6	IO_L51N_6/VREF_6	AF37	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	VCCO_7	AA29	
7	VCCO_7	Y29	
7	VCCO_7	W29	
7	VCCO_7	V29	
7	VCCO_7	U29	
7	VCCO_7	T29	
7	VCCO_7	R29	
7	VCCO_7	AA28	
7	VCCO_7	Y28	
7	VCCO_7	W28	
7	VCCO_7	V28	
7	VCCO_7	U28	
7	VCCO_7	T28	
6	VCCO_6	AU39	
6	VCCO_6	AN39	
6	VCCO_6	AJ39	
6	VCCO_6	AD39	
6	VCCO_6	AW37	
6	VCCO_6	AN35	
6	VCCO_6	AJ35	
6	VCCO_6	AD35	
6	VCCO_6	AR33	
6	VCCO_6	AL33	
6	VCCO_6	AH29	
6	VCCO_6	AG29	
6	VCCO_6	AF29	
6	VCCO_6	AE29	
6	VCCO_6	AD29	
6	VCCO_6	AC29	
6	VCCO_6	AB29	
6	VCCO_6	AG28	
6	VCCO_6	AF28	
6	VCCO_6	AE28	
6	VCCO_6	AD28	
6	VCCO_6	AC28	
6	VCCO_6	AB28	
5	VCCO_5	AW33	